



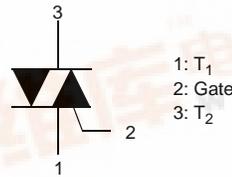
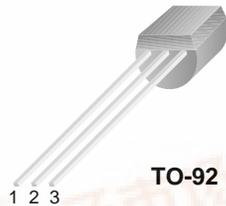
February 2008

# FKN08PN60S

## TRIAC (Silicon Bidirectional Thyristor)

### Application Explanation

- Switching mode power supply, light dimmer, electric flasher unit, hair drier
- TV sets, stereo, refrigerator, washing machine
- Electric blanket, solenoid driver, small motor control
- Photo copier, electric tool



### Absolute Maximum Ratings T<sub>a</sub> = 25°C unless otherwise noted

| Symbol                               | Parameter                         | Value  | Rating     | Units            |
|--------------------------------------|-----------------------------------|--|------------|------------------|
| V <sub>DRM</sub><br>V <sub>RRM</sub> | Peak Repetitive Off-State Voltage | Sine Wave 50 to 60Hz, Gate Open  | 600        | V                |
| I <sub>T (RMS)</sub>                 | RMS On-State Current              | Commercial frequency, sine full wave<br>360° conduction, T <sub>c</sub> = 70°C | 0.8        | A                |
| I <sub>TSM</sub>                     | Surge On-State Current            | Sinewave half cycle, peak value,<br>non-repetitive                             | 60Hz<br>8  | A                |
| I <sup>2</sup> t                     | I <sup>2</sup> t for Fusing       | Value corresponding to halfwave,<br>surge on-state current, tp=8.33ms          | 0.26       | A <sup>2</sup> s |
| P <sub>GM</sub>                      | Peak Gate Power Dissipation       |  | 5          | W                |
| P <sub>G (AV)</sub>                  | Average Gate Power Dissipation    |  | 0.1        | W                |
| V <sub>GM</sub>                      | Peak Gate Voltage                 |  | 5          | V                |
| I <sub>GM</sub>                      | Peak Gate Current                 |  | 1          | A                |
| T <sub>J</sub>                       | Junction Temperature              |  | - 40 ~ 125 | °C               |
| T <sub>STG</sub>                     | Storage Temperature               |  | - 40 ~ 125 | °C               |

### Thermal Characteristics

| Symbol           | Parameter                                       | Value | Units |
|------------------|---|-------|-------|
| R <sub>θJC</sub> | Thermal Resistance, Junction to Case (note1)    | 45    | °C/W  |
| R <sub>θJA</sub> | Thermal Resistance, Junction to Ambient (note2) | 160   | °C/W  |

Note1: Infinite cooling condition.

Note2: JESD51-10 ( Test Borad: FR4 3.0"\*4.5"\*0.062", Minimum land pad)

FKN08PN60S — TRIAC (Silicon Bidirectional Thyristor)



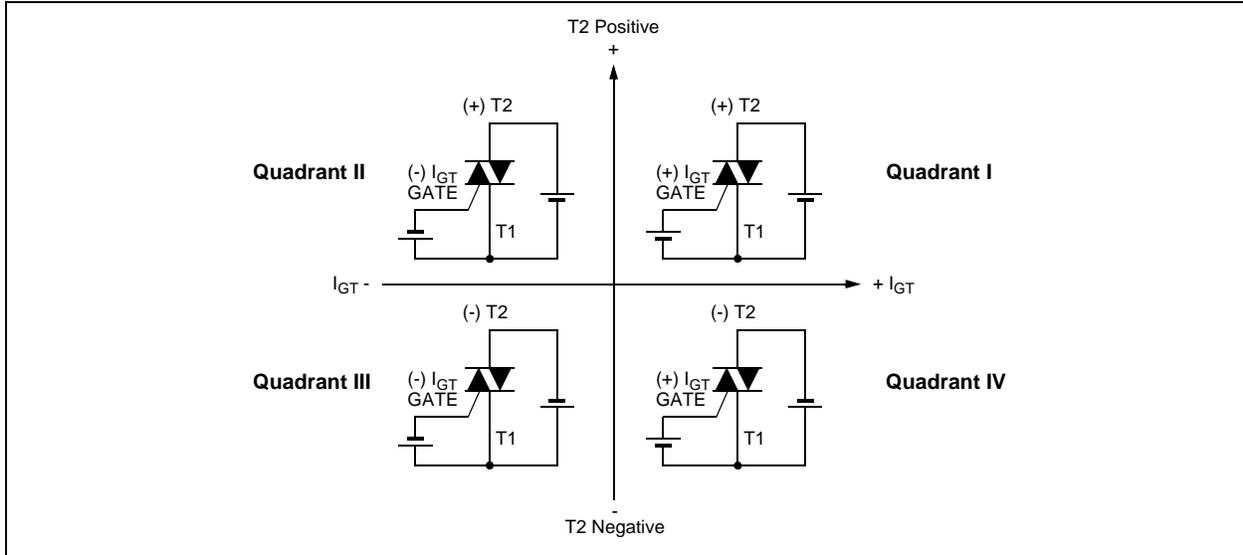
**Electrical Characteristics**  $T_C = 25^\circ\text{C}$  unless otherwise noted

| Symbol                 | Parameter  | Test Condition  | Min.            | Typ. | Max. | Units            |    |
|------------------------|--|---|-----------------|------|------|------------------|----|
| $I_{DRM}$<br>$I_{RRM}$ | Repetitive Peak Off-State Current  | $V_{DRM}/V_{RRM}$ applied   | -               | -    | 100  | $\mu\text{A}$    |    |
| $V_{TM}$               | On-State Voltage   | $T_C=25^\circ\text{C}$ , $I_{TM}=1.12\text{A}$<br>Instantaneous measurement | -               | -    | 1.8  | V                |    |
| $V_{GT}$               | Gate Trigger Voltage (Note 2)  | $V_D=12\text{V}$ , $R_L=100\Omega$  | T2(+), Gate (+) | -    | -    | 2.0              | V  |
|                        |  |   | T2(+), Gate (-) | -    | -    | 2.0              | V  |
|                        |  |   | T2(-), Gate (-) | -    | -    | 2.0              | V  |
| $I_{GT}$               | Gate Trigger Current (Note 2)  | $V_D=12\text{V}$ , $R_L=100\Omega$  | T2(+), Gate (+) | -    | -    | 5                | mA |
|                        |  |   | T2(+), Gate (-) | -    | -    | 5                | mA |
|                        |  |   | T2(-), Gate (-) | -    | -    | 5                | mA |
| $V_{GD}$               | Gate Non-Trigger Voltage   | $T_J=125^\circ\text{C}$ , $V_D=1/2V_{DRM}$                                  | 0.2             | -    | -    | V                |    |
| $I_H$                  | Holding Current (I, II, III)   | $V_D = 12\text{V}$ , $I_{TM} = 200\text{mA}$                                | -               | -    | 15   | mA               |    |
| $I_L$                  | Latching Current   | $V_D = 12\text{V}$ , $I_G = 10\text{mA}$                                    | I, III          | -    | -    | 15               | mA |
|                        |  |   | II              | -    | -    | 20               | mA |
| dv/dt(s)               | Critical Rate of Rise of Off-State Voltage   | $V_{DRM} = 63\%$ Rated, $T_J = 125^\circ\text{C}$ ,<br>Exponential Rise     | 20              | -    | -    | V/ $\mu\text{s}$ |    |
| dv/dt(c)               | Critical-Rate of Rise of Off-State Commutating Voltage (di/dt=-0.7A/ $\mu\text{s}$ ) |   | 3.0             | -    | -    | V/ $\mu\text{s}$ |    |

**Commutation dv/dt test**

| $V_{DRM}$<br>(V) | Test Condition  | Commutating voltage and current waveforms<br>(inductive load) |
|------------------|---|---|
| FKN08PN60S       | 1. Junction Temperature<br>$T_J=125^\circ\text{C}$<br>2. Rate of decay of on-state commutating current (di/dt) <sub>C</sub><br>3. Peak off-state voltage<br>$V_D = 300\text{V}$ |   |

### Quadrant Definitions for a Triac

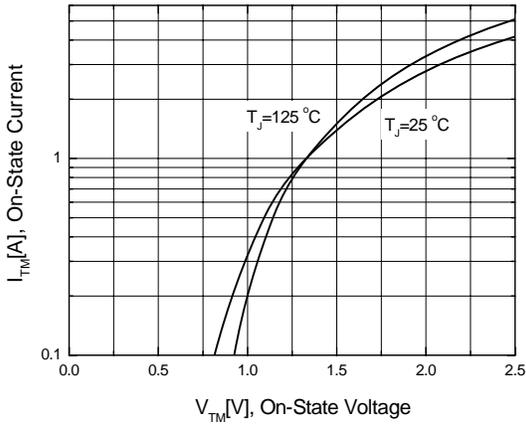


### Package Marking and Ordering Information

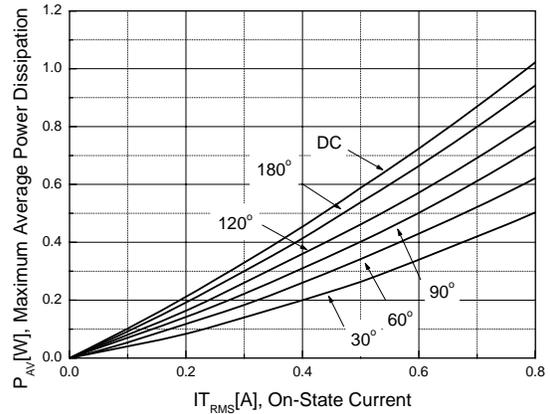
| Device Marking | Device     | Package | Packing | Tape Width | Quantity |
|----------------|------------|---------|---------|------------|----------|
| K08PN60S       | FKN08PN60S | TO-92   | BULK    | --         | --       |

## Typical Performance Characteristics

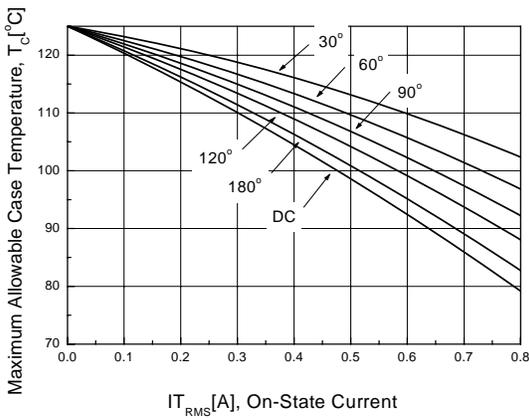
**Figure 1. On-State Characteristics**



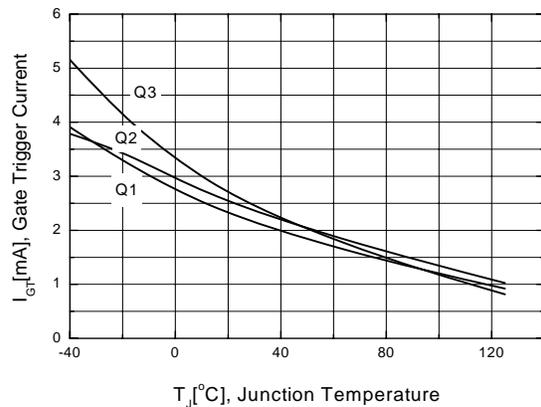
**Figure 2. Power Dissipation**



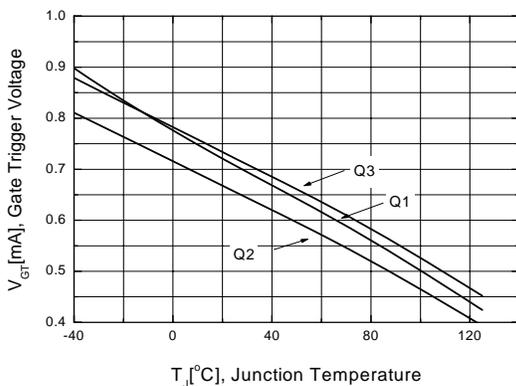
**Figure 3. RMS Current Rating**



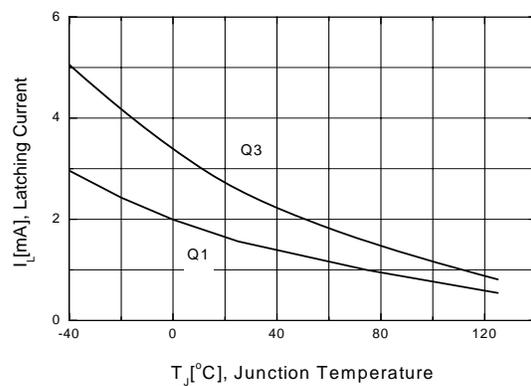
**Figure 4. Typical Gate Trigger Current vs Junction Temperature**



**Figure 5. Typical Gate Voltage vs Junction Temperature**

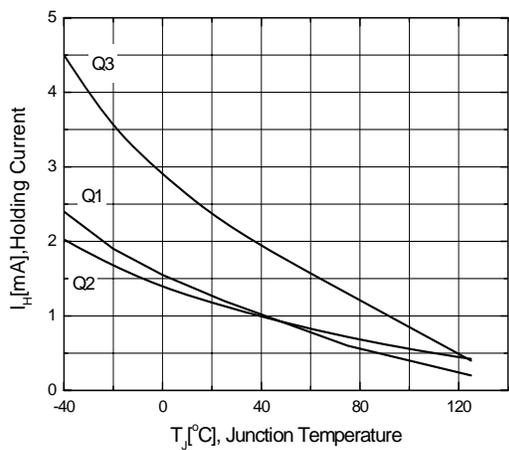


**Figure 6. Typical Latching Current vs Junction Temperature**

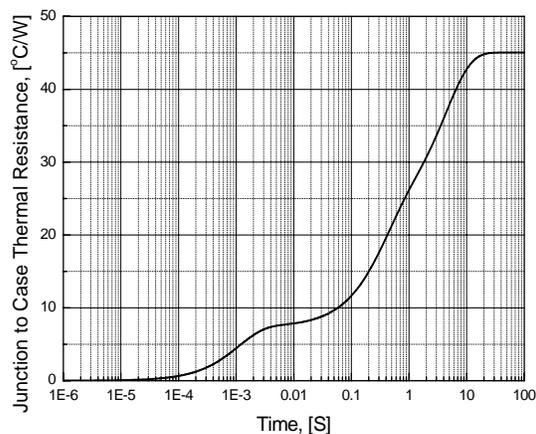


**Typical Performance Characteristics** (Continued)

**Figure7. Typical Holding Current vs Junction Temperature**

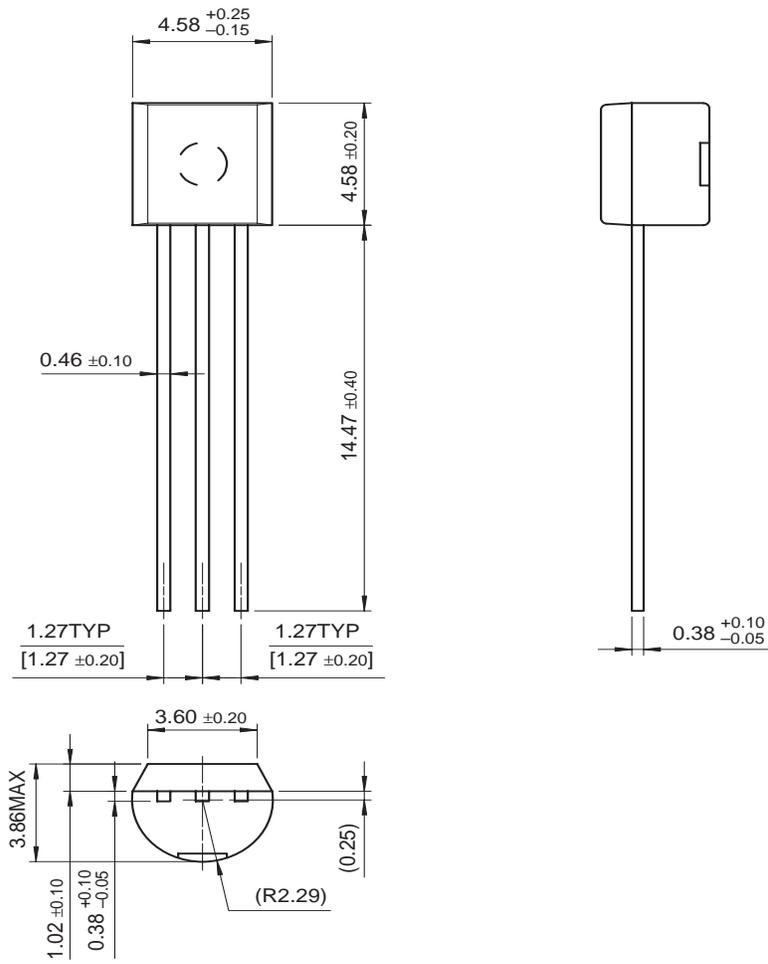


**Figure8. Junction to Case Thermal Resistance**



# Package Dimension

## TO-92





**TRADEMARKS**

The following are registered and unregistered trademarks and service marks Fairchild Semiconductor owns or is authorized to use and is not intended to be an exhaustive list of all such trademarks.

|                                     |   |                            |                               |
|-------------------------------------|---|----------------------------|-------------------------------|
| ACEx®                               | Green FPS™  | Power247®                  | SuperSOT™-8                   |
| Build it Now™                       | Green FPS™ e-Series™  | POWEREDGE®                 | SyncFET™                      |
| CorePLUS™                           | GTO™  | Power-SPM™                 | The Power Franchise®          |
| CROSSVOLT™                          | i-Lo™   | PowerTrench®               | <b>the power</b><br>franchise |
| CTL™                                | IntelliMAX™   | Programmable Active Droop™ | TinyBoost™                    |
| Current Transfer Logic™             | ISOPLANAR™  | QFET®                      | TinyBuck™                     |
| EcoSPARK®                           | MegaBuck™   | QS™                        | TinyLogic®                    |
| <b>F</b> ®                          | MICROCOUPLER™   | QT Optoelectronics™        | TINYOPTO™                     |
| Fairchild®                          | MicroFET™   | Quiet Series™              | TinyPower™                    |
| Fairchild Semiconductor®            | MicroPak™   | RapidConfigure™            | TinyPWM™                      |
| FACT Quiet Series™                  | MillerDrive™  | SMART START™               | TinyWire™                     |
| FACT®                               | Motion-SPM™   | SPM®                       | µSerDes™                      |
| FAST®                               | OPTOLOGIC®  | STEALTH™                   | UHC®                          |
| FastvCore™                          | OPTOPLANAR®   | SuperFET™                  | UniFET™                       |
| FPS™                                |  ® | SuperSOT™-3                | VCX™                          |
| FRFET®                              | PDP-SPM™  | SuperSOT™-6                |                               |
| Global Power Resource <sup>SM</sup> | Power220®   |                            |                               |

**DISCLAIMER**

FAIRCHILD SEMICONDUCTOR RESERVES THE RIGHT TO MAKE CHANGES WITHOUT FURTHER NOTICE TO ANY PRODUCTS HEREIN TO IMPROVE RELIABILITY, FUNCTION, OR DESIGN. FAIRCHILD DOES NOT ASSUME ANY LIABILITY ARISING OUT OF THE APPLICATION OR USE OF ANY PRODUCT OR CIRCUIT DESCRIBED HEREIN; NEITHER DOES IT CONVEY ANY LICENSE UNDER ITS PATENT RIGHTS, NOR THE RIGHTS OF OTHERS. THESE SPECIFICATIONS DO NOT EXPAND THE TERMS OF FAIRCHILD'S WORLDWIDE TERMS AND CONDITIONS, SPECIFICALLY THE WARRANTY THEREIN, WHICH COVERS THESE PRODUCTS.

**LIFE SUPPORT POLICY**

FAIRCHILD'S PRODUCTS ARE NOT AUTHORIZED FOR USE AS CRITICAL COMPONENTS IN LIFE SUPPORT DEVICES OR SYSTEMS WITHOUT THE EXPRESS WRITTEN APPROVAL OF FAIRCHILD SEMICONDUCTOR CORPORATION.

As used herein:

- Life support devices or systems are devices or systems which, (a) are intended for surgical implant into the body, or (b) support or sustain life, and (c) whose failure to perform when properly used in accordance with instructions for use provided in the labeling, can be reasonably expected to result in significant injury to the user.
- A critical component is any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

**PRODUCT STATUS DEFINITIONS**

**Definition of Terms**

| Datasheet Identification | Product Status         | Definition   |
|--------------------------|------------------------|--|
| Advance Information      | Formative or In Design | This datasheet contains the design specifications for product development. Specifications may change in any manner without notice.   |
| Preliminary              | First Production       | This datasheet contains preliminary data; supplementary data will be published at a later date. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve design. |
| No Identification Needed | Full Production        | This datasheet contains final specifications. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve design.   |
| Obsolete                 | Not In Production      | This datasheet contains specifications on a product that has been discontinued by Fairchild semiconductor. The datasheet is printed for reference information only.                                      |